PARTIAL SEMICONDUCTOR WAFER PROCESSING

ABSTRACT OF THE DISCLOSURE

Partial wafer processing is achieved by down loading the wafer map of the whole wafer from a host (2) and if the partial wafer (half or quarter) contains the reference die (4) move table to a locator die (5) and upload locator die coordinates to wafer map data host (6) and remove other half or quadrants die coordinates from the map (10). If the partial wafer is not in the first half or first quadrant position wafertable to auxiliary reference die, find out which half or quadrant partial wafer belongs (8) and compute auxiliary reference die coordinates from locator die coordinates (9) and then using auxiliary die coordinates as information remove other quadrant or half die coordinates from the map (10).

Figure 6

162162

G00002